

CC1050

Single Chip Very Low Power RF Transmitter

Applications

- *Very low power UHF wireless data transmitters*
- *315 / 433 / 868 and 915 MHz ISM/SRD band systems*
- *RKE – Remote Keyless Entry*
- *Home automation*
- *Wireless alarm and security systems*
- *AMR – Automatic Meter Reading*
- *Low power telemetry*
- *Game Controllers and advanced toys*

Product Description

CC1050 is a true single-chip UHF transmitter designed for very low power and very low voltage wireless applications. The circuit is mainly intended for the ISM (Industrial, Scientific and Medical) and SRD (Short Range Device) frequency bands at 315, 433, 868 and 915 MHz, but can easily be programmed for operation at other frequencies in the 300-1000 MHz range.

The main operating parameters of **CC1050** can be programmed via an easy-to-interface serial bus, thus making **CC1050** a very flexible and easy to use transmitter. In a typical system **CC1050** will be used together with a microcontroller and a few external passive components.

CC1050 is based on Chipcon's SmartRF® technology in 0.35 µm CMOS.



Features

- True single chip UHF RF transmitter
- Very low current consumption
- Frequency range 300 – 1000 MHz
- Programmable output power –20 to 12 dBm
- Small size (TSSOP-24 package)
- Low supply voltage (2.1 V to 3.6 V)
- Very few external components required
- Single-ended antenna connection
- FSK data rate up to 76.8 kBaud
- Complies with EN 300 220 and FCC CFR47 part 15
- Programmable frequency in 250 Hz steps makes crystal temperature drift compensation possible without TCXO
- Suitable for frequency hopping protocols
- Development Kit available
- Easy-to-use software for generating the **CC1050** configuration data

Table of Contents

| | |
|---|----|
| Absolute Maximum Ratings | 4 |
| Operating Conditions | 4 |
| Electrical Specifications | 4 |
| Pin Assignment | 7 |
| Application Circuit | 9 |
| Configuration Overview | 10 |
| Configuration Software | 11 |
| 3-wire Serial Configuration Interface | 12 |
| Microcontroller Interface | 14 |
| Signal interface | 15 |
| Frequency programming | 17 |
| VCO | 17 |
| VCO and PLL self-calibration | 17 |
| VCO current control | 21 |
| Power management | 21 |
| Output Matching | 24 |
| Output power programming | 25 |
| Crystal oscillator | 26 |
| Optional LC Filter | 27 |
| System Considerations and Guidelines | 28 |
| PCB Layout Recommendations | 29 |
| Antenna Considerations | 29 |
| Configuration registers | 30 |
| Package Description (TSSOP-24) | 38 |
| Soldering Information | 38 |
| Plastic Tube Specification | 38 |

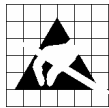
| | |
|---|----|
| Carrier Tape and Reel Specification | 38 |
| Ordering Information | 39 |
| General Information | 39 |
| Address Information | 40 |

Absolute Maximum Ratings

| Parameter | Min. | Max. | Units | Condition |
|------------------------------|------|---------------------|-------|-----------|
| Supply voltage, VDD | -0.3 | 5.0 | V | |
| Voltage on any pin | -0.3 | VDD+0.3, max 5.0 | V | |
| Input RF level | | 10 | dBm | |
| Storage temperature range | -50 | 150 | °C | |
| Reflow soldering temperature | | 260 | °C | T = 10 s |

Under no circumstances the absolute maximum ratings given above should be violated. Stress exceeding one or more of

the limiting values may cause permanent damage to the device.



Caution! ESD sensitive device.
Precaution should be used when handling the device in order to prevent permanent damage.

Operating Conditions

| Parameter | Min. | Typ. | Max. | Unit | Condition / Note |
|-------------------------------------|------|------|------|------|--|
| RF Frequency Range | 300 | | 1000 | MHz | Programmable in steps of 250 Hz |
| Operating ambient temperature range | -40 | | 85 | °C | |
| Supply voltage | 2.1 | 3.0 | 3.6 | V | Note: The same supply voltage should be used for digital (DVDD) and analogue (AVDD) power. |

Electrical Specifications

T_c = 25°C, VDD = 3.0 V if nothing else stated

| Parameter | Min. | Typ. | Max. | Unit | Condition / Note |
|------------------------------------|------------|----------|---------|------------|---|
| Transmit Section | | | | | |
| Transmit data rate | 0.6 | | 76.8 | kBaud | NRZ or Manchester encoding. 76.8 kBaud equals 76.8 kbit/s using NRZ coding. See page 15. |
| Binary FSK frequency separation | 0 | | 65 | kHz | The frequency separation is programmable in 250 Hz steps. 65 kHz is the maximum guaranteed separation at 1 MHz reference frequency. Larger separations can be achieved at higher reference frequencies. |
| Output power 433 MHz 868 MHz | -20 -20 | | 12 8 | dBm dBm | Delivered to 50 Ω load. The output power is programmable. |
| RF output impedance 433/868 MHz | | 110 / 70 | | Ω | Transmit mode. For matching details see p.24. |

| Parameter | Min. | Typ. | Max. | Unit | Condition / Note |
|--|----------------|----------------------|----------------|----------------|---|
| Spurious emission | | | -36 | dBm | Complies with EN 300 220 |
| Harmonics | | -20 | | dBc | An external LC should be used to reduce harmonics emission to comply with SRD requirements. See p.27. |
| Frequency Synthesiser Section | | | | | |
| Crystal Oscillator Frequency | 3 | | 16 | MHz | Crystal frequency can be 3-4, 6-8 or 9-16 MHz. Recommended frequencies are 3.6864, 7.3728, 11.0592 and 14.7456. See page 26 for details. |
| Crystal frequency accuracy requirement | | ± 50 ± 25 | | ppm | 433 MHz 868 MHz The crystal frequency accuracy and drift (ageing and temperature dependency) will determine the frequency accuracy of the transmitted signal. |
| Crystal operation | | Parallel | | | C3 and C4 are loading capacitors, see page 26 |
| Crystal load capacitance | 12 12 12 | 22 16 16 | 30 30 16 | pF pF pF | 3-8 MHz, 22 pF recommended 6-8 MHz, 16 pF recommended 9-16 MHz, 16 pF recommended |
| Crystal oscillator start-up time | | 4 1.5 2 | | ms ms ms | 3.6864 MHz, 16 pF load 7.3728 MHz, 16 pF load 16 MHz, 16 pF load |
| Output signal phase noise | | -80 | | dBc/Hz | At 100 kHz offset from carrier |
| PLL lock time | | 200 | | μ s | Up to 1 MHz frequency step |
| PLL turn-on time, crystal oscillator on in power down mode | | 250 | | μ s | Crystal oscillator running |
| Digital Inputs/Outputs | | | | | |
| Logic "0" input voltage | 0 | | 0.3*VDD | V | |
| Logic "1" input voltage | 0.7*VDD | | VDD | V | |
| Logic "0" output voltage | 0 | | 0.4 | V | Output current -2.5 mA, 3.0 V supply voltage |
| Logic "1" output voltage | 2.5 | | VDD | V | Output current 2.5 mA, 3.0 V supply voltage |
| Logic "0" input current | NA | | -1 | μ A | Input signal equals GND |
| Logic "1" input current | NA | | 1 | μ A | Input signal equals VDD |
| DI setup time | 20 | | | ns | TX mode, minimum time DI must be ready before the positive edge of DCLK |
| DI hold time | 10 | | | ns | TX mode, minimum time DI must be held after the positive edge of DCLK |

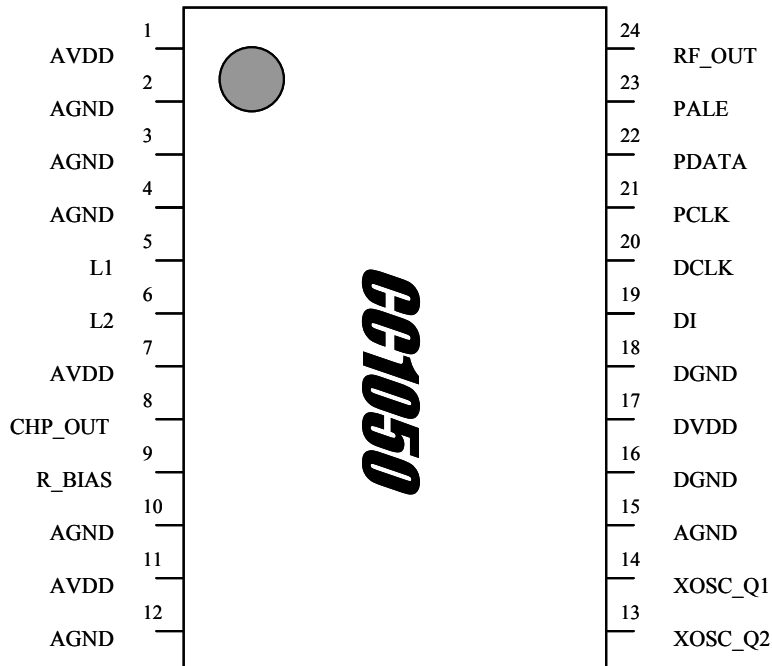
| Parameter | Min. | Typ. | Max. | Unit | Condition / Note |
|--|------|-----------------|------|----------------|--|
| Serial interface (PCLK, PDATA and PALE) timing specification | | | | | See Table 2 page 13 |
| Current Consumption | | | | | |
| Power Down mode | | 0.2 | 1 | μA | Oscillator core off |
| Current Consumption, transmit mode 433/868 MHz: | | | | | |
| P=0.01mW (-20dBm) | | 5.5/8.0 | | mA | The output power is delivered to a 50Ω load |
| P=0.3mW (-5dBm) | | 7.3/10.0 | | mA | |
| P=1mW (0dBm) | | 9.1/14.2 | | mA | |
| P=3mW (5dBm) | | 13.3/17.7 | | mA | |
| P=6mW (8dBm) | | 15.9/24.9 | | mA | |
| P=16mW (12dBm) | | 23.3/NA | | mA | |
| Current Consumption, crystal osc. | | 30 80 105 | | μA μA μA | 3-8 MHz, 16 pF load 9-14 MHz, 12 pF load 14-16 MHz, 16 pF load |
| Current Consumption, crystal osc. and bias | | 400 | | μA | |
| Current Consumption, crystal osc., bias and synthesiser | | 4.0 5.5 | | mA mA | < 500 MHz > 500 MHz |

Pin Assignment

| Pin no. | Pin name | Pin type | Description |
|---------|----------|----------------------|---|
| 1 | AVDD | Power (A) | Power supply (3 V) for analog modules (PA) |
| 2 | AGND | Ground (A) | Ground connection (0 V) for analog modules (PA) |
| 3 | AGND | Ground (A) | Ground connection (0 V) for analog modules (PA) |
| 4 | AGND | Ground (A) | Ground connection (0 V) for analog modules (VCO and prescaler) |
| 5 | L1 | Analog input | Connection no 1 for external VCO tank inductor |
| 6 | L2 | Analog input | Connection no 2 for external VCO tank inductor |
| 7 | AVDD | Power (A) | Power supply (3 V) for analog modules (VCO and prescaler) |
| 8 | CHP_OUT | Analog output | Charge pump current output when external loop filter is used The pin can also be used as PLL Lock indicator. Output is high when PLL is in lock. |
| 9 | R_BIAS | Analog output | Connection for external precision bias resistor (82 k Ω , \pm 1%) |
| 10 | AGND | Ground (A) | Ground connection (0 V) for analog modules (backplane) |
| 11 | AVDD | Power (A) | Power supply (3 V) for analog modules (general) |
| 12 | AGND | Ground (A) | Ground connection (0 V) for analog modules (general) |
| 13 | XOSC_Q2 | Analog output | Crystal, pin 2 |
| 14 | XOSC_Q1 | Analog input | Crystal, pin 1, or external clock input |
| 15 | AGND | Ground (A) | Ground connection (0 V) for analog modules (guard) |
| 16 | DGND | Ground (D) | Ground connection (0 V) for digital modules (substrate) |
| 17 | DVDD | Power (D) | Power supply (3 V) for digital modules |
| 18 | DGND | Ground (D) | Ground connection (0 V) for digital modules |
| 19 | DI | Digital input | Data input in transmit mode |
| 20 | DCLK | Digital output | Clock for data in transmit mode |
| 21 | PCLK | Digital input | Programming clock for 3-wire bus |
| 22 | PDATA | Digital input/output | Programming data for 3-wire bus. Programming data input for write operation, programming data output for read operation |
| 23 | PALE | Digital input | Programming address latch enable for 3-wire bus |
| 24 | RF_OUT | RF output | RF signal output to antenna |

A=Analog, D=Digital

(Top View)



Circuit Description

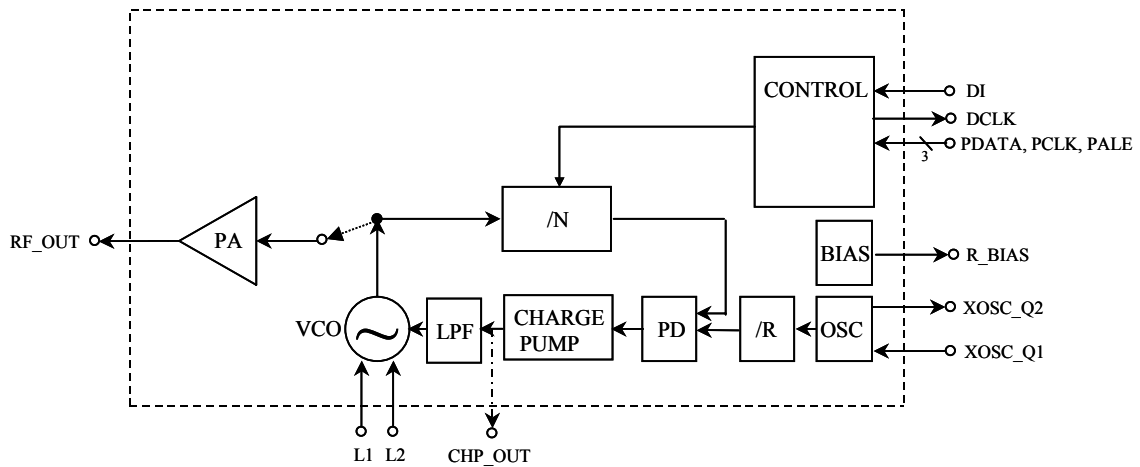


Figure 1. Simplified block diagram

A simplified block diagram of **CC1050** is shown in Figure 1. Only signal pins are shown.

The voltage controlled oscillator (VCO) output signal is fed directly to the power amplifier (PA). The RF output is frequency shift keyed (FSK) by the digital bit stream fed to the pin DI. The single ended PA makes the antenna interface and matching very easy.

The frequency synthesiser generates the local oscillator signal which is fed to the PA in transmit mode. The frequency synthesiser consists of a crystal oscillator (OSC), phase detector (PD), charge pump (CHARGE PUMP), VCO, and frequency dividers (/R and /N). An external crystal must be connected to XOSC, and only an external inductor is required for the VCO.

The 3-wire digital serial interface (CONTROL) is used for configuration.

Application Circuit

Very few external components are required for the operation of CC1050. A typical application circuit is shown Figure 2. Component values are shown in Table 1.

Output matching

C1, C2 and L2 are used to match the transmitter to 50 Ω . See Output Matching p.24 for details.

VCO inductor

The VCO is completely integrated except for the inductor L1. For further details see p. 17.

Component values for the matching network and VCO inductor are easily calculated using the SmartRF® Studio software.

Crystal oscillator

C3 and C4 are the loading capacitors for the crystal. See page 26 for details.

Additional filtering

Additional filtering (e.g. a low pass LC-filter) may be used in order to reduce the harmonic emission. See also Optional LC Filter p.27 for further information.

Power supply decoupling and filtering

Power supply decoupling and filtering must be used (not shown in the application circuit). The placement and size of the decoupling capacitors and the power supply filtering are very important to achieve the optimum performance. Chipcon provides a reference design (CC1050EB) that should be followed very closely.

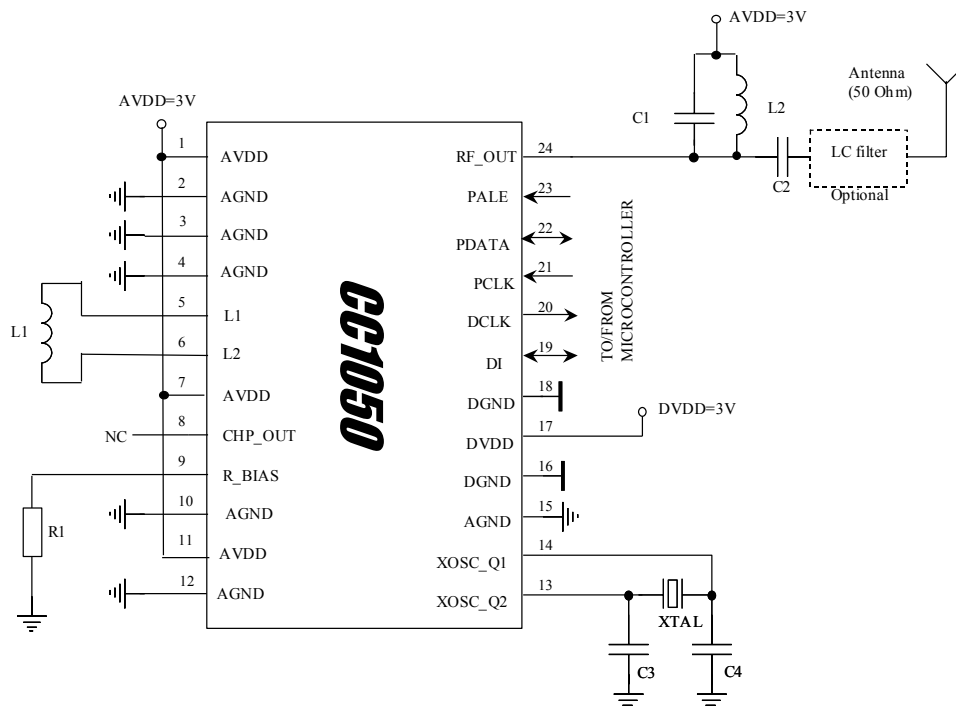


Figure 2. Typical **CC1050** application circuit

| Item | 315 MHz | 433 MHz | 868 MHz | 915 MHz |
|------|------------------------------------|------------------------------------|------------------------------------|------------------------------------|
| C1 | 5.6 pF, 5%, C0G, 0603 | 12 pF, 5%, C0G, 0603 | 4.7 pF, 5%, C0G, 0603 | 4.7 pF, 5%, C0G, 0603 |
| C2 | 8.2 pF, 5%, C0G, 0603 | 6.8 pF, 5%, C0G, 0603 | 5.6 pF, 5%, C0G, 0603 | 5.6 pF, 5%, C0G, 0603 |
| C3* | 15 pF, 5%, C0G, 0603 | 15 pF, 5%, C0G, 0603 | 15 pF, 5%, C0G, 0603 | 15 pF, 5%, C0G, 0603 |
| C4* | 15 pF, 5%, C0G, 0603 | 15 pF, 5%, C0G, 0603 | 15 pF, 5%, C0G, 0603 | 15 pF, 5%, C0G, 0603 |
| L1 | 56 nH, 5%, 0603 | 33 nH, 5%, 0603 | 5.6 nH, 5%, 0603 | 5.6 nH, 5%, 0603 |
| L2 | 20 nH, 10%, 0805 | 6.2 nH, 10%, 0805 | 2.5 nH, 10%, 0805 | 2.5 nH, 10%, 0805 |
| R1 | 82 k Ω , 1%, 0603 | 82 k Ω , 1%, 0603 | 82 k Ω , 1%, 0603 | 82 k Ω , 1%, 0603 |
| XTAL | 14.7456 MHz crystal, 16 pF load | 14.7456 MHz crystal, 16 pF load | 14.7456 MHz crystal, 16 pF load | 14.7456 MHz crystal, 16 pF load |

Notes:

Items shaded are different for different frequencies.

Component values for 868 and 915 MHz are equal.

*) C3 and C4 will depend on the crystal load capacitance, see page 26.

Table 1. Bill of materials for the application circuit

Configuration Overview

CC1050 can be configured to achieve the best performance for different applications. Through the programmable configuration registers the following key parameters can be programmed:

- Transmit mode / power-down / power-up mode
- RF output power
- Frequency synthesiser key parameters: RF output frequency, FSK

frequency separation (deviation),
crystal oscillator reference frequency

- Crystal oscillator power-up / power down
- Data rate and data format (NRZ, Manchester coded or UART interface)
- Synthesiser lock indicator mode
- Modulation spectrum shaping

Configuration Software

Chipcon provides users of **CC1050** with a software program, SmartRF® Studio (Windows interface) that generates all necessary **CC1050** configuration data based on the user's selections of various parameters. These hexadecimal numbers will then be the necessary input to the microcontroller for the configuration of

CC1050. In addition the program will provide the user with the component values needed for the output matching circuit and the VCO inductor.

Figure 3 shows the user interface of the **CC1050** configuration software.

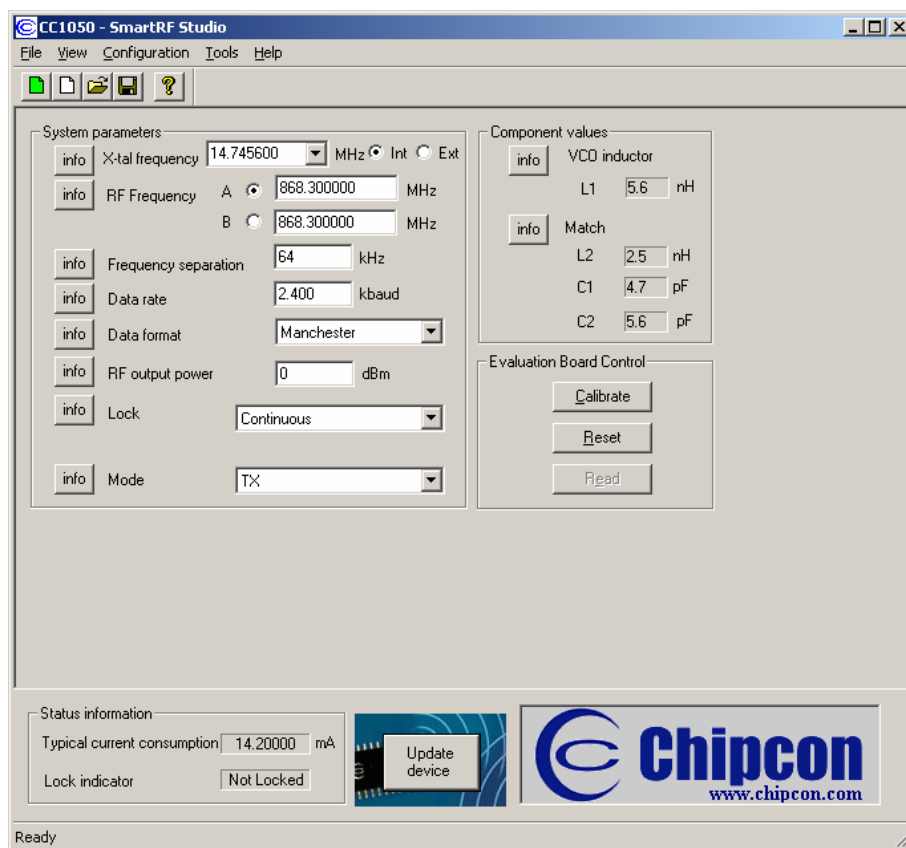


Figure 3. SmartRF® Studio user interface

3-wire Serial Configuration Interface

CC1050 is configured via a simple 3-wire interface (PDATA, PCLK and PALE). There are 19 8-bit configuration registers, each addressed by a 7-bit address. A Read/Write bit initiates a read or write operation. A full configuration of **CC1050** requires sending 19 data frames of 16 bits each (7 address bits, R/W bit and 8 data bits). The time needed for a full configuration depend on the PCLK frequency. With a PCLK frequency of 10 MHz the full configuration is done in less than 30 μ s. Setting the device in power down mode requires sending one frame only and will in this case take less than 2 μ s. All registers are also readable.

In each write-cycle 16 bits are sent on the PDATA-line. The seven most significant bits of each data frame (A6:0) are the address-bits. A6 is the MSB (Most Significant Bit) of the address and is sent as the first bit. The next bit is the R/W bit (high for write, low for read). During address and R/W bit transfer the PALE (Program Address Latch Enable) must be kept low. The 8 data-bits are then transferred (D7:0). See Figure 4.

The timing for the programming is also shown in Figure 4 with reference to Table 2. The clocking of the data on PDATA is done on the negative edge of PCLK. When the last bit, D0, of the 8 data-bits has been loaded, the data word is loaded in the internal configuration register.

The configuration data is stored in internal RAM and is valid after power-down mode, but not when the power-supply is turned off. The registers can be programmed in any order.

The configuration registers can also be read by the microcontroller via the same configuration interface. The seven address bits are sent first, then the R/W bit set low to initiate the data read-back. **CC1050** then returns the data from the addressed register. PDATA is in this case used as an output and must be tri-stated (or set high in the case of an open collector pin) by the microcontroller during the data read-back (D7:0). The read operation is illustrated in Figure 5.

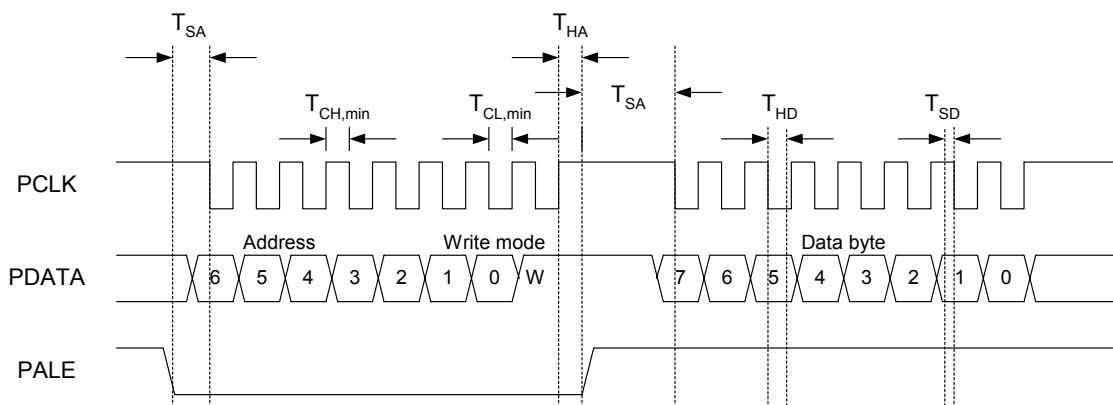


Figure 4. Configuration registers write operation

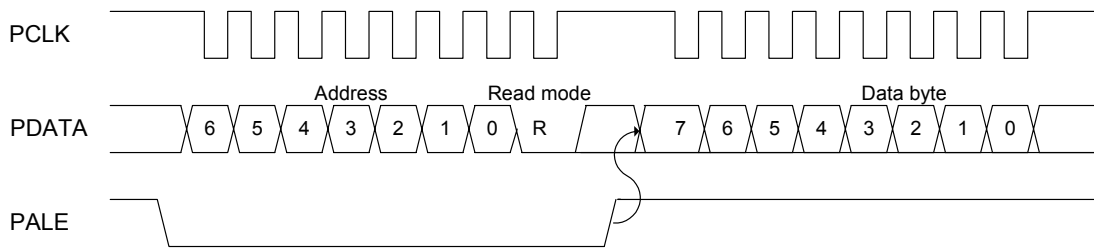


Figure 5. Configuration registers read operation

| Parameter | Symbol | Min | Max | Units | Conditions |
|--------------------------|---------------------|-----|-----|-------|--|
| PCLK, clock frequency | F_{CLOCK} | - | 10 | MHz | |
| PCLK low pulse duration | $T_{\text{CL,min}}$ | 50 | | ns | The minimum time PCLK must be low. |
| PCLK high pulse duration | $T_{\text{CH,min}}$ | 50 | | ns | The minimum time PCLK must be high. |
| PALE setup time | T_{SA} | 10 | - | ns | The minimum time PALE must be low before negative edge of PCLK. |
| PALE hold time | T_{HA} | 10 | - | ns | The minimum time PALE must be held low after the <i>positive</i> edge of PCLK. |
| PDATA setup time | T_{SD} | 10 | - | ns | The minimum time data on PDATA must be ready before the negative edge of PCLK. |
| PDATA hold time | T_{HD} | 10 | - | ns | The minimum time data must be held at PDATA, after the negative edge of PCLK. |
| Rise time | T_{rise} | | 100 | ns | The maximum rise time for PCLK and PALE |
| Fall time | T_{fall} | | 100 | ns | The maximum fall time for PCLK and PALE |

Note: The set-up- and hold-times refer to 50% of VDD.

Table 2. Serial interface, timing specification

Microcontroller Interface

Used in a typical system, **CC1050** will interface to a microcontroller. This microcontroller must be able to:

- Program **CC1050** into different modes via the 3-wire serial configuration interface (PDATA, PCLK and PALE).
- Interface to the synchronous data signal interface (DI and DCLK).

- Optionally the microcontroller can do data encoding / decoding.
- Optionally the microcontroller can monitor the frequency lock status from pin CHP_OUT (LOCK).

Connecting the microcontroller

The microcontroller uses 3 output pins for the configuration interface (PDATA, PCLK and PALE). PDATA should be a bi-directional pin for data read-back. The DI pin is used for data to be transmitted. DCLK providing the data timing should be connected to a microcontroller input. Optionally another pin can be used to monitor the LOCK signal (available at the CHP_OUT pin). This signal is logic level high when the PLL is in lock. See Figure 6.

The microcontroller pins connected to PDATA and PCLK can be used for other purposes when the configuration interface is not used. PDATA and PCLK are high impedance inputs as long as PALE high.

PALE has an internal pull-up resistor and should be left open (tri-stated by the microcontroller) or set to a high level during power down mode in order to prevent a trickle current flowing in the pull-up.

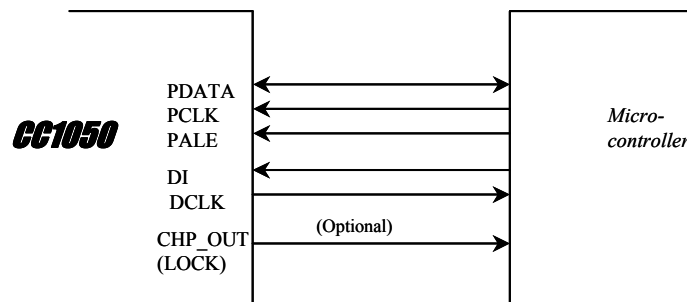


Figure 6. Microcontroller interface

Signal interface

The signal interface consists of DI and DCLK and is used for the data to be transmitted. DI is the data input line and DCLK provides a synchronous clock during data transmission.

The **CC1050** can be used with NRZ (Non-Return-to-Zero) data or Manchester (also known as bi-phase-level) encoded data.

CC1050 can be configured for three different data formats:

Synchronous NRZ mode. **CC1050** provides the data clock at DCLK, and DI is used as data input. Data is clocked into **CC1050** at the rising edge of DCLK. The data is modulated at RF without encoding. **CC1050** can be configured for the data rates 0.6, 1.2, 2.4, 4.8, 9.6, 19.2, 38.4 or 76.8 kbit/s. See Figure 7.

Synchronous Manchester encoded mode. **CC1050** provides the data clock at DCLK, and DI is used as data input. Data is clocked into **CC1050** at the rising edge of DCLK and should be in NRZ format. The data is modulated at RF with Manchester code. The encoding is done by **CC1050**. In this mode **CC1050** can be configured for

the data rates 0.3, 0.6, 1.2, 2.4, 4.8, 9.6, 19.2 or 38.4 kbit/s. The 38.4 kbit/s rate corresponds to the maximum 76.8 kBaud due to the Manchester encoding. See Figure 8.

Transparent Asynchronous UART mode. In transmit mode DI is used as data input. The data is modulated at RF without synchronisation or encoding. Data rates in the range from 0.6 to 76.8 kBaud can be used. See Figure 9.

Manchester encoding

In the *Synchronous Manchester encoded mode* **CC1050** uses Manchester coding when modulating the data. The Manchester code is based on transitions; a "0" is encoded as a low-to-high transition, a "1" is encoded as a high-to-low transition. See Figure 10.

The Manchester code ensures that the signal has a constant DC component, which is necessary in some FSK demodulators. Using this mode also ensures compatibility with CC400/CC900 designs.

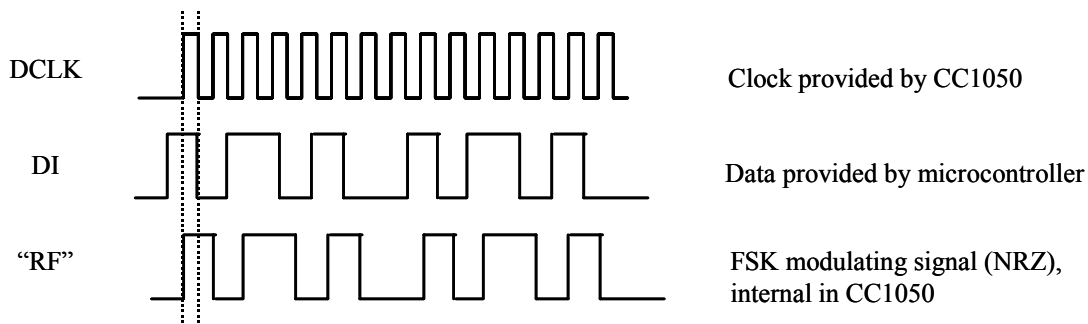


Figure 7. Synchronous NRZ mode

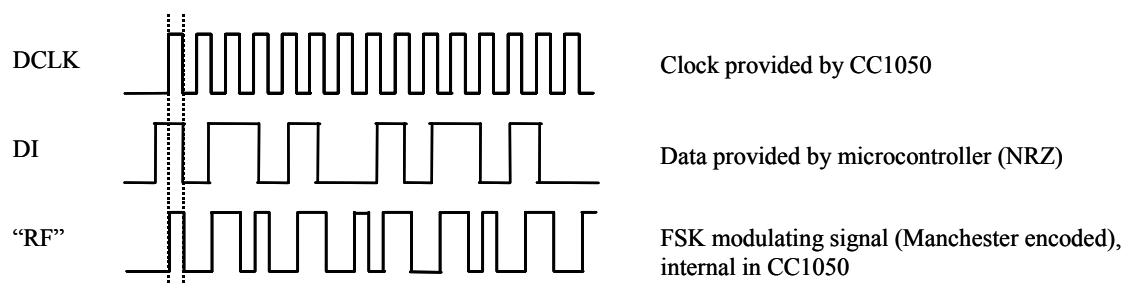


Figure 8. Synchronous Manchester encoded mode

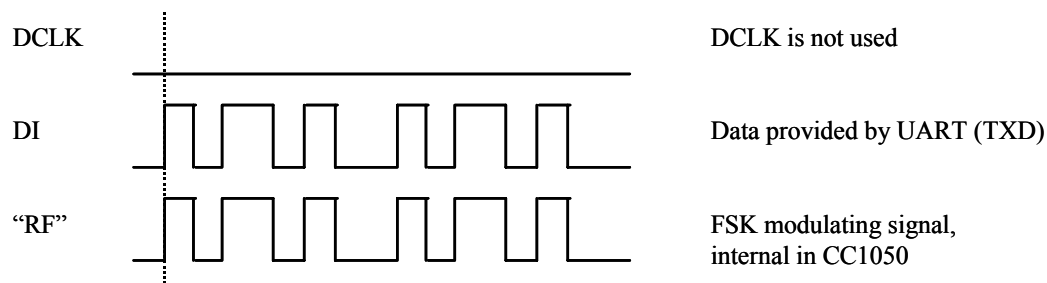


Figure 9. Transparent Asynchronous UART mode

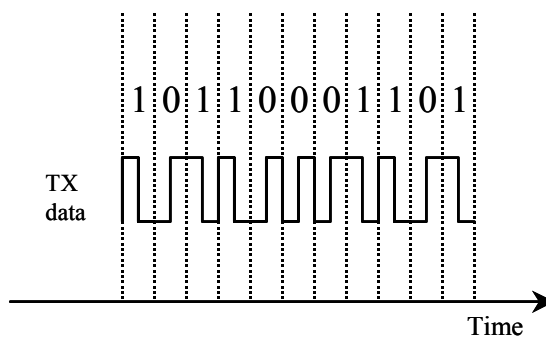


Figure 10. Manchester encoding

Frequency programming

The operation frequency is set by programming the frequency word in the configuration registers. There are two frequency words registers, termed *A* and *B*, which can be programmed to two different frequencies in order to switch fast between two different channels. Frequency word *A* or *B* is selected by the *F_REG* bit in the *MAIN* register.

The frequency word is 24 bits (3 bytes) located in *FREQ_2A:FREQ_1A:FREQ_0A* and *FREQ_2B:FREQ_1B:FREQ_0B* for the *A* and *B* word respectively.

The FSK frequency separation is programmed in the *FSEP1:FSEP0* registers (11 bits).

The frequency word *FREQ* is calculated by:

$$f_{VCO} = f_{ref} \cdot \frac{FREQ + 8192}{16384}$$

where the reference frequency is the crystal oscillator clock divided by *REFDIV* (4 bits in the *PLL* register), a number between 2 and 15:

$$f_{ref} = \frac{f_{xosc}}{REFDIV}$$

The equation above gives the VCO frequency, that is, f_{VCO} is the f_0 frequency for transmit mode (lower FSK frequency).

The upper FSK frequency is given by:

$$f_1 = f_0 + f_{sep}$$

where f_{sep} is set by the separation word:

$$f_{sep} = f_{ref} \cdot \frac{FSEP}{16384}$$

VCO

Only one external inductor (L1) is required for the VCO. The inductor will determine the operating frequency range of the circuit. It is important to place the inductor as close to the pins as possible in order to reduce stray inductance. It is recommended to use a high Q, low tolerance inductor for best performance.

Typical tuning range for the integrated varactor is 20-25%.

Component values for various frequencies are given in Table 1. Component values for other frequencies can be found using the SmartRF® Studio software.

VCO and PLL self-calibration

To compensate for supply voltage, temperature and process variations the VCO and PLL must be calibrated. The calibration is done automatically and sets maximum VCO tuning range and optimum charge pump current for PLL stability. After setting up the device at the operating frequency, the self-calibration can be initiated by setting the *CAL_START* bit. The calibration result is stored internally in the chip, and is valid as long as power is not turned off. If large supply voltage variations (more than 0.5 V) or temperature variations (more than 40 degrees) occur after calibration, a new calibration should be performed.

The self-calibration is controlled through the *CAL* register (see configuration registers description p. 30). The *CAL_COMPLETE* bit indicates complete calibration. The user can poll this bit, or simply wait for 26 ms (calibration wait time when *CAL_WAIT* = 1). The wait time is proportional to the internal PLL reference frequency. The lowest permitted reference frequency (1 MHz) gives 26 ms wait time, which is therefore the worst case.

| Reference frequency [MHz] | Calibration time [ms] |
|---------------------------|-----------------------|
| 2.4 | 11 |
| 2.0 | 13 |
| 1.5 | 18 |
| 1.0 | 26 |

The *CAL_COMPLETE* bit can also be monitored at the *CHP_OUT* (LOCK) pin (configured by *LOCK_SELECT[3:0]*) and used as an interrupt input to the microcontroller.

The *CAL_START* bit must be set to 0 by the microcontroller after the calibration is done.

There are separate calibration values for the two frequency registers. If the two frequencies, A and B, differ more than 1

MHz, or different VCO currents are used (*VCO_CURRENT[3:0]* in the *CURRENT* register) the calibration should be done separately. The *CAL_DUAL* bit in the *CAL* register controls dual or separate calibration.

The single calibration algorithm using separate calibration for two frequencies is illustrated in Figure 11.

In Figure 12 the dual calibration algorithm is shown.

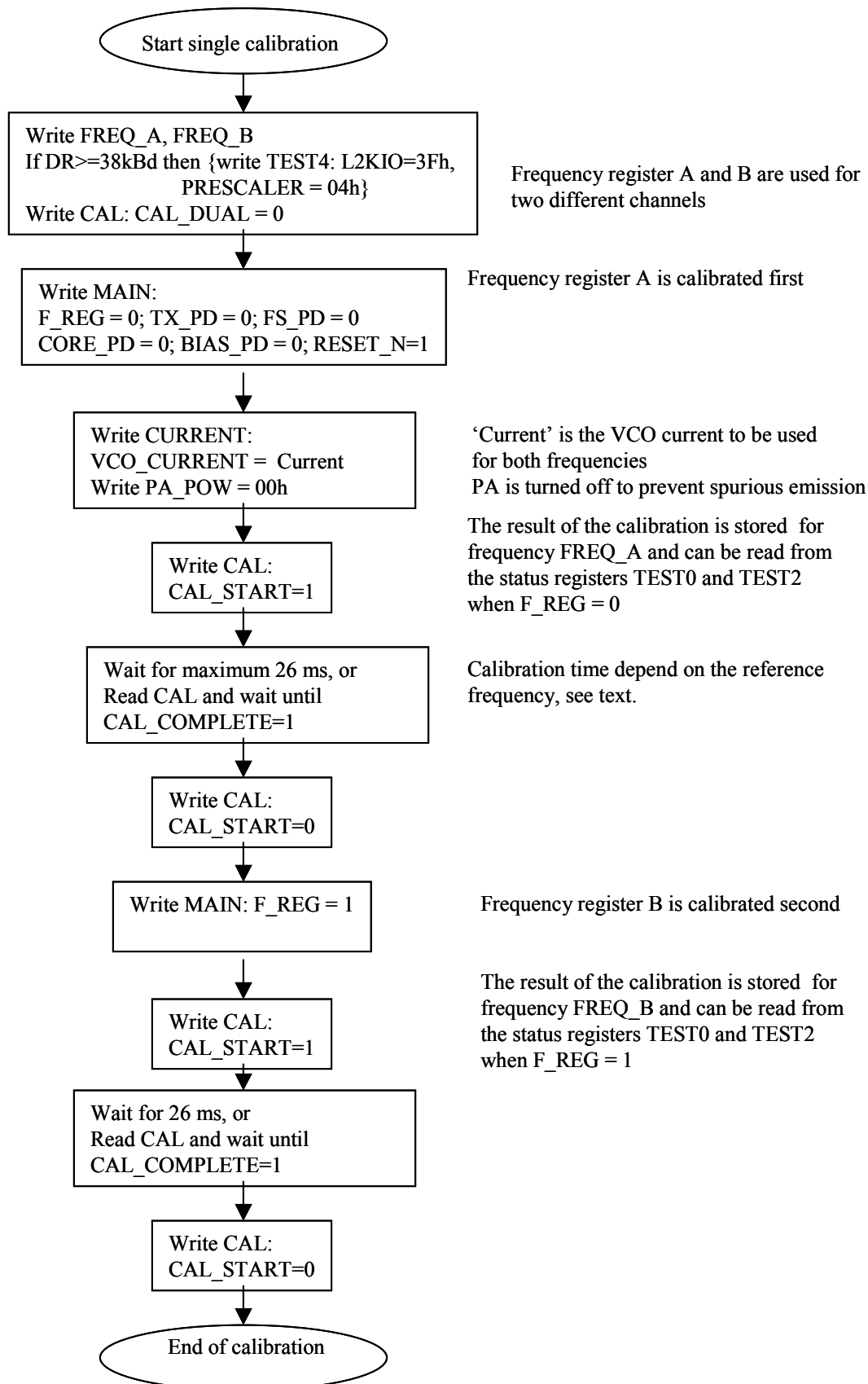


Figure 11. Single calibration algorithm for two different frequencies

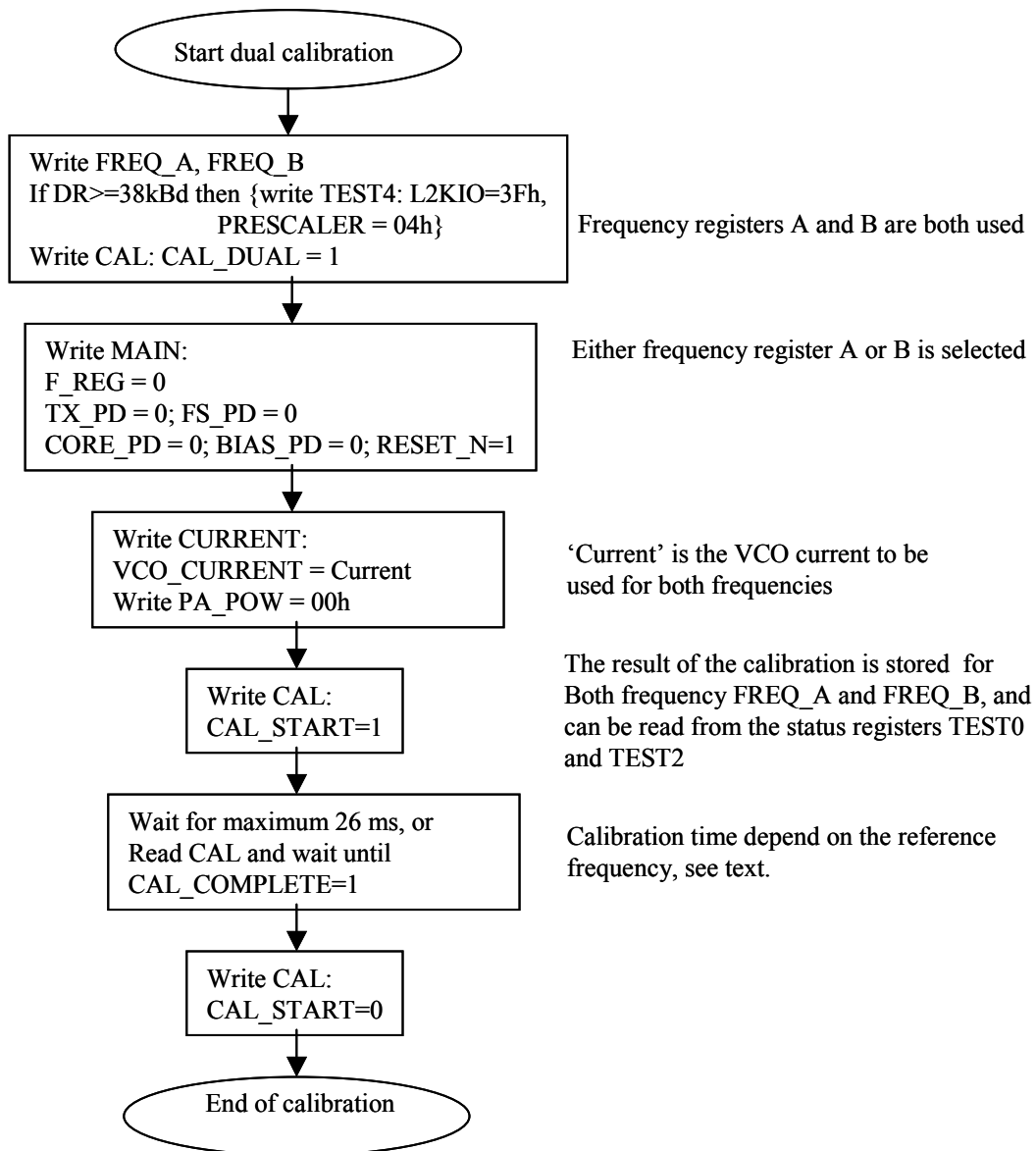


Figure 12. Dual calibration algorithm

VCO current control

The VCO current is programmable and should be set according to operating frequency and output power. Recommended settings for the *VCO_CURRENT* bits in the *CURRENT* register are shown in the tables on page 32.

The bias current for the PA buffers are also programmable. Recommended settings for the *PA_DRIVE* bits in the *CURRENT* register are shown in the tables on page 32.

Power management

CC1050 offers great flexibility for power management in order to meet strict power consumption requirements in battery operated applications. Power Down mode is controlled through the *MAIN* register. There are separate bits to control the TX part, the frequency synthesiser and the crystal oscillator. This individual control can be used to optimise for lowest possible current consumption in a certain application.

A typical power-on and initialising sequence for minimum power consumption is shown in Figure 13 and Figure 14.

PALE should be tri-stated or set to a high level during power down mode in order to prevent a trickle current from flowing in the internal pull-up resistor.

PA_POW should be set to 00h during power down mode to ensure lowest possible leakage current.

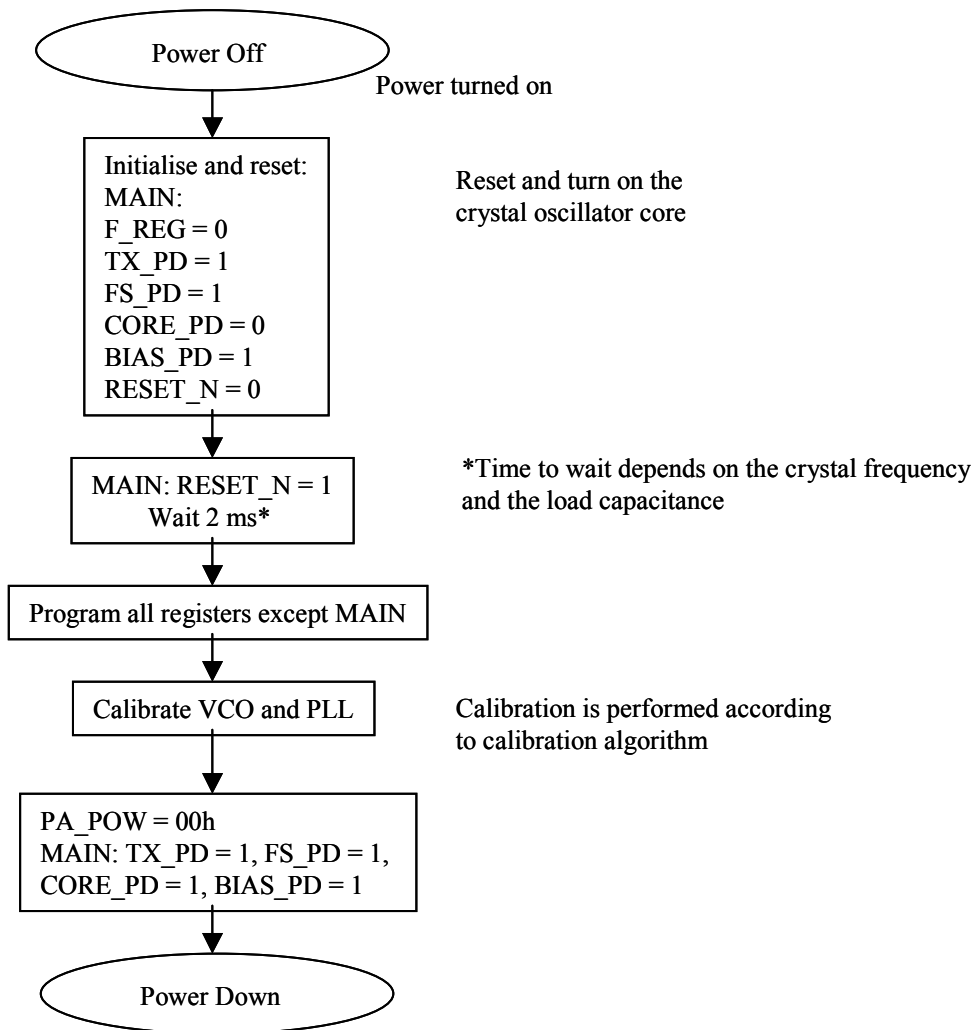


Figure 13. Initializing sequence

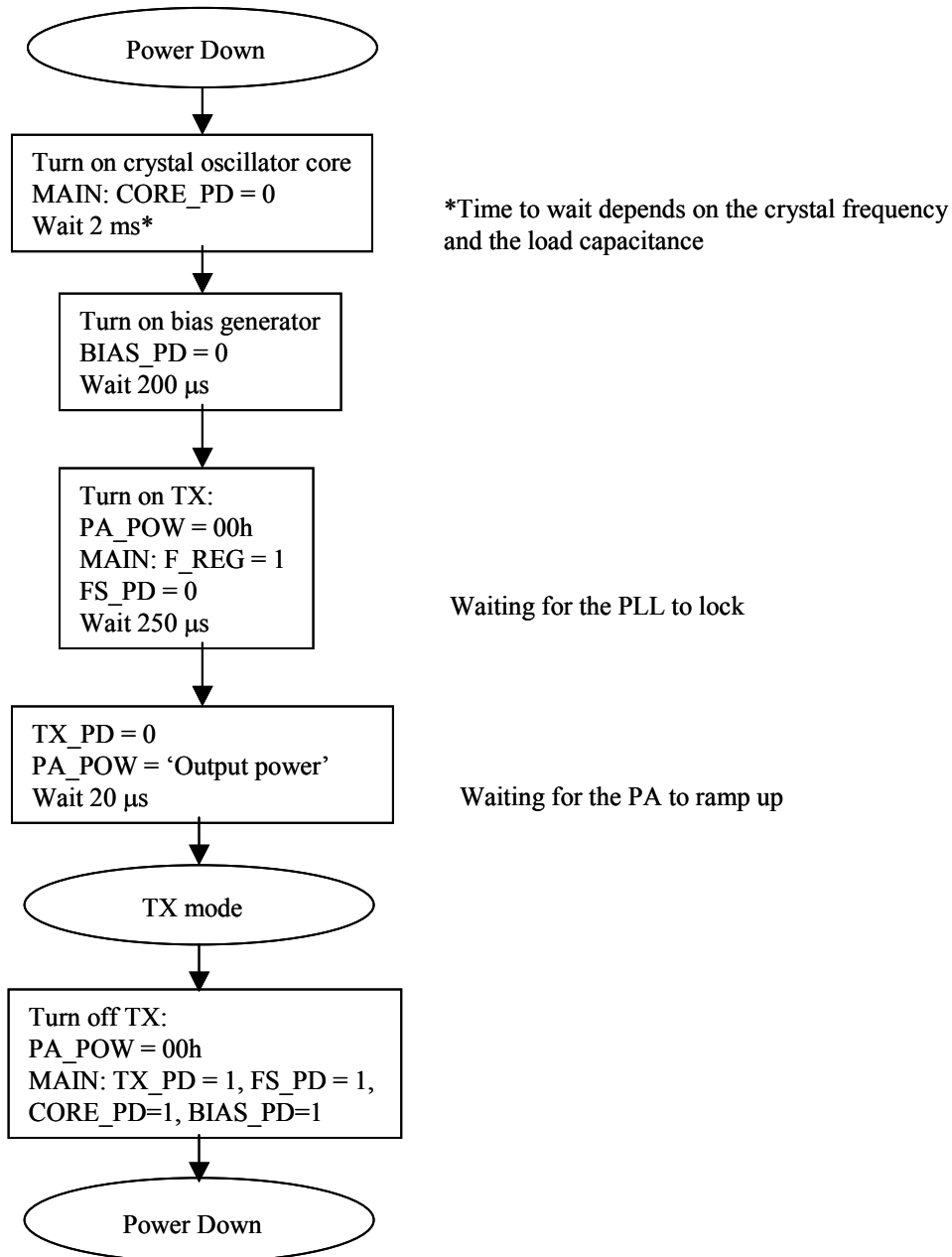


Figure 14. Sequence for activating TX mode

Output Matching

A few passive external components ensures match in TX mode. The matching network is shown in Figure 15. Component values for various frequencies

are given in Table 1. Component values for other frequencies can be found using the configuration software.

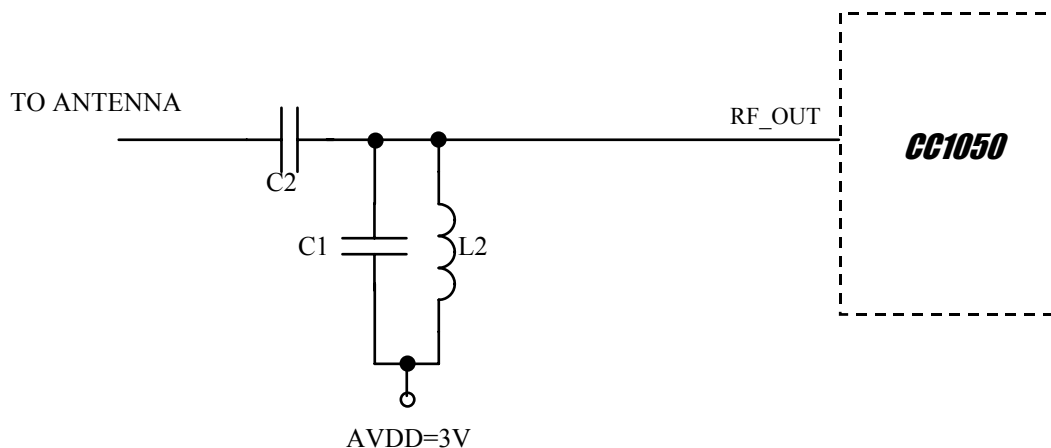


Figure 15. Output matching network

Output power programming

The RF output power is programmable and controlled by the PA_POWER register.

Table 3 shows the closest programmable value for output powers in steps of 1 dB. The typical current consumption is also shown.

In power down mode the PA_POWER should be set to 00h for minimum leakage current.

| Output power [dBm] | RF frequency 433 MHz | | RF frequency 868 MHz | |
|--------------------|----------------------|--------------------------------|----------------------|--------------------------------|
| | PA_POWER [hex] | Current consumption, typ. [mA] | PA_POWER [hex] | Current consumption, typ. [mA] |
| -20 | 01 | 5.5 | 02 | 8.0 |
| -19 | 01 | 5.5 | 02 | 8.0 |
| -18 | 01 | 5.5 | 02 | 8.0 |
| -17 | 02 | 5.7 | 03 | 8.3 |
| -16 | 02 | 5.7 | 03 | 8.3 |
| -15 | 02 | 5.7 | 04 | 8.5 |
| -14 | 02 | 5.7 | 04 | 8.5 |
| -13 | 03 | 6.0 | 05 | 8.7 |
| -12 | 03 | 6.0 | 05 | 8.7 |
| -11 | 04 | 6.2 | 06 | 8.9 |
| -10 | 04 | 6.2 | 06 | 8.9 |
| -9 | 05 | 6.5 | 07 | 9.1 |
| -8 | 05 | 6.5 | 08 | 9.4 |
| -7 | 06 | 6.8 | 09 | 9.6 |
| -6 | 07 | 7.0 | 0A | 9.8 |
| -5 | 08 | 7.3 | 0B | 10.0 |
| -4 | 09 | 7.5 | 0D | 10.4 |
| -3 | 0A | 7.8 | 0E | 10.6 |
| -2 | 0C | 8.3 | 0F | 10.9 |
| -1 | 0D | 8.5 | 40 | 13.4 |
| 0 | 0F | 9.1 | 50 | 14.2 |
| 1 | 40 | 10.5 | 60 | 15.0 |
| 2 | 50 | 11.5 | 70 | 15.7 |
| 3 | 50 | 11.5 | 80 | 16.3 |
| 4 | 60 | 12.4 | 90 | 17.0 |
| 5 | 70 | 13.3 | A0 | 17.7 |
| 6 | 80 | 14.7 | C0 | 19.1 |
| 7 | 90 | 15.1 | E0 | 20.0 |
| 8 | A0 | 15.9 | FF | 24.9 |
| 9 | C0 | 17.6 | | |
| 10 | E0 | 19.2 | | |
| 11 | F0 | 20.0 | | |
| 12 | FF | 23.3 | | |

Table 3. Output power settings and typical current consumption

Crystal oscillator

CC1050 has an advanced amplitude regulated crystal oscillator. A high current is used to start up the oscillations. When the amplitude builds up, the current is reduced to what is necessary to maintain a 600 mVpp amplitude. This ensures a fast start-up, keeps the current consumption as well as the drive level to a minimum and makes the oscillator insensitive to ESR variations.

An external clock signal or the internal crystal oscillator can be used as main frequency reference. An external clock signal should be connected to XOSC_Q1, while XOSC_Q2 should be left open. The XOSC_BYPASS bit in the XOSC register should be set when an external clock signal is used.

The crystal frequency should be in the range 3-4, 6-8 or 9-16 MHz. Because the crystal frequency is used as reference for the data rate (as well as other internal functions), the following frequencies are recommended: 3.6864, 7.3728, 11.0592 or 14.7456 MHz. These frequencies will give accurate data rates. The crystal frequency range is selected by XOSC_FREQ1:0 in the MODEM0 register.

To operate in synchronous mode at data rates different from the standards at 1.2, 2.4, 4.8 kBaud and so on, the crystal frequency can be scaled. The data rate (DR) will change proportionally to the new crystal frequency (f). To calculate the new crystal frequency:

$$f_{xtal_new} = f_{xtal} \frac{DR_{new}}{DR}$$

Using the internal crystal oscillator, the crystal must be connected between XOSC_Q1 and XOSC_Q2. The oscillator is designed for parallel mode operation of the crystal. In addition loading capacitors (C3 and C4) for the crystal are required. The loading capacitor values depend on the total load capacitance, C_L , specified for the crystal. The total load capacitance seen between the crystal terminals should equal C_L for the crystal to oscillate at the specified frequency.

$$C_L = \frac{1}{\frac{1}{C_3} + \frac{1}{C_4}} + C_{parasitic}$$

The parasitic capacitance is constituted by pin input capacitance and PCB stray capacitance. Typically the total parasitic capacitance is 8 pF. A trimming capacitor may be placed across C4 for initial tuning if necessary.

The crystal oscillator circuit is shown in Figure 16. Typical component values for different values of C_L are given in Table 4.

The initial tolerance, temperature drift, ageing and load pulling should be carefully specified in order to meet the required frequency accuracy in a certain application.

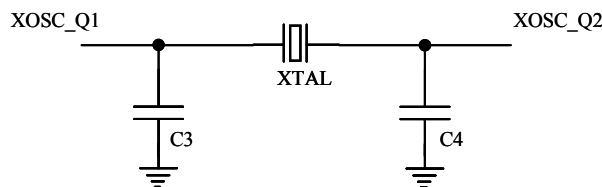


Figure 16. Crystal oscillator circuit

| Item | $C_L = 12 \text{ pF}$ | $C_L = 16 \text{ pF}$ | $C_L = 22 \text{ pF}$ |
|------|-----------------------|-----------------------|-----------------------|
| C3 | 6.8 pF | 15 pF | 27 pF |
| C4 | 6.8 pF | 15 pF | 27 pF |

Table 4. Crystal oscillator component values

Optional LC Filter

An optional LC filter may be added between the antenna and the matching network in certain applications. The filter will reduce the emission of harmonics.

A Pi-type filter topology is shown in Figure 17. Component values are given in Table 5. The filter is designed for 50 Ω terminations. The component values may have to be tuned to compensate for layout parasitics.

A T-Type LC filter can be used to further attenuate harmonics if the Pi-type filter is not sufficient. A T-type filter provides much better stop-band attenuation than a Pi-type filter due to improved insulation between input and output. For more details refer to Application Note *AN028 LC Filter with Improved High-Frequency Attenuation* available from the Chipcon web site.

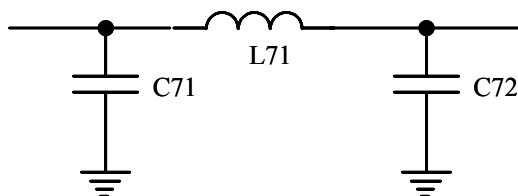


Figure 17. LC filter

| Item | 315 MHz | 433 MHz | 868 MHz | 915 MHz |
|------|---------|---------|---------|---------|
| C71 | 30 pF | 20 pF | 10 pF | 10 pF |
| C72 | 30 pF | 20 pF | 10 pF | 10 pF |
| L71 | 15 nH | 12 nH | 5.6 nH | 4.7 nH |

Table 5. LC filter component values

System Considerations and Guidelines

SRD regulations

International regulations and national laws regulate the use of radio receivers and transmitters. SRDs (Short Range Devices) for licence free operation are allowed to operate in the 433 and 868-870 MHz bands in most European countries. In the United States such devices operate in the 260–470 and 902-928 MHz bands. **CC1050** is designed to meet the requirements for operation in all these bands. A summary of the most important aspects of these regulations can be found in Application Note *AN001 SRD regulations for licence free transceiver operation*, available from Chipcon's web site.

Low cost systems

In systems where low cost is of great importance the **CC1050** is the ideal choice. Very few external components keep the total cost at a minimum. The oscillator crystal can then be a low cost crystal with 50 ppm frequency tolerance.

Battery operated systems

In low power applications the power down mode should be used when not being active. Depending on the start-up time requirement, the oscillator core can be powered during power down. See page 21 for information on how effective power management can be implemented.

Crystal drift compensation

A unique feature in **CC1050** is the very fine frequency resolution of 250 Hz. This can be used to do the temperature

compensation of the crystal if the temperature drift curve is known and a temperature sensor is included in the system. Even initial adjustment can be done using the frequency programmability. This eliminates the need for an expensive TCXO and trimming in some applications. In less demanding applications a crystal with low temperature drift and low ageing could be used without further compensation. A trimmer capacitor in the crystal oscillator circuit (in parallel with C4) could be used to set the initial frequency accurately.

High output power systems

The CHP_OUT (LOCK) pin can be configured to control an power amplifier. This is controlled by *LOCK_SELECT* in the *LOCK* register.

Frequency hopping spread spectrum systems

Due to the very fast frequency shift properties of the PLL, the **CC1050** is also suitable for frequency hopping systems. Hop rates of 1-100 hops/s are usually used depending on the bit rate and the amount of data to be sent during each transmission. The two frequency registers (*FREQ_A* and *FREQ_B*) are designed such that the 'next' frequency can be programmed while the 'present' frequency is used. The switching between the two frequencies is done through the *MAIN* register.

PCB Layout Recommendations

A two layer PCB is highly recommended. The bottom layer of the PCB should be the “ground-layer”. Chipcon provide reference designs that should be followed in order to achieve the best performance.

The top layer should be used for signal routing, and the open areas should be filled with metallisation connected to ground using several vias.

The ground pins should be connected to ground as close as possible to the package pin using individual vias. The de-coupling capacitors should also be placed as close as possible to the supply pins and connected to the ground plane by separate vias.

The external components should be as small as possible and surface mount devices should be used.

Precaution should be used when placing the microcontroller in order to avoid interference with the RF circuitry.

In certain applications where the ground plane for the digital circuitry is expected to be noisy, the ground plane may be split in an analogue and a digital part. All AGND pins and AVDD de-coupling capacitors should be connected to the analogue ground plane. All DGND pins and DVDD de-coupling capacitors should be connected to the digital ground. The connection between the two ground planes should be implemented as a star connection with the power supply ground.

A development kit with a fully assembled PCB is available, and can be used as a guideline for layout.

Antenna Considerations

CC1050 can be used together with various types of antennas. The most common antennas for short range communication are monopole, helical and loop antennas.

Monopole antennas are resonant antennas with a length corresponding to one quarter of the electrical wavelength ($\lambda/4$). They are very easy to design and can be implemented simply as a “piece of wire” or even integrated into the PCB.

Non-resonant monopole antennas shorter than $\lambda/4$ can also be used, but at the expense of range. In size and cost critical applications such an antenna may very well be integrated into the PCB.

Helical antennas can be thought of as a combination of a monopole and a loop antenna. They are a good compromise in size critical applications. But helical antennas tend to be more difficult to optimise than the simple monopole.

Loop antennas are easy to integrate into the PCB, but are less effective due to

difficult impedance matching because of their very low radiation resistance.

For low power applications the $\lambda/4$ -monopole antenna is recommended giving the best range and because of its simplicity.

The length of the $\lambda/4$ -monopole antenna is given by:

$$L = 7125 / f$$

where f is in MHz, giving the length in cm. An antenna for 869 MHz should be 8.2 cm, and 16.4 cm for 434 MHz.

The antenna should be connected as close as possible to the IC. If the antenna is located away from the input pin the antenna should be matched to the feeding transmission line (50Ω).

For a more thorough primer on antennas, please refer to Application Note AN003 *SRD Antennas* available from Chipcon’s web site.

Configuration registers

The configuration of **CC1050** is done by programming the 19 8-bit configuration registers. The configuration data based on selected system parameters are most easily found by using the SmartRF®

Studio software. A complete description of the registers are given in the following tables. After a RESET is programmed all the registers have default values.

REGISTER OVERVIEW

| ADDRESS | Byte Name | Description |
|---------|-----------|--|
| 00h | MAIN | MAIN Register |
| 01h | FREQ_2A | Frequency Register 2A |
| 02h | FREQ_1A | Frequency Register 1A |
| 03h | FREQ_0A | Frequency Register 0A |
| 04h | FREQ_2B | Frequency Register 2B |
| 05h | FREQ_1B | Frequency Register 1B |
| 06h | FREQ_0B | Frequency Register 0B |
| 07h | FSEP1 | Frequency Separation Register 1 |
| 08h | FSEP0 | Frequency Separation Register 0 |
| 09h | CURRENT | Current Consumption Control Register |
| 0Ah | XOSC | Crystal Oscillator Control Register |
| 0Bh | PA_POW | PA Output Power Control Register |
| 0Ch | PLL | PLL Control Register |
| 0Dh | LOCK | LOCK Status Register and signal select to CHP_OUT (LOCK) pin |
| 0Eh | CAL | VCO Calibration Control and Status Register |
| 0Fh | Not used | Not used |
| 10h | Not used | Not used |
| 11h | MODEM0 | Modem Control Register |
| 12h | Not used | Not used |
| 13h | FSCTRL | Frequency Synthesiser Control Register |
| 14h | | Reserved |
| 15h | | Reserved |
| 16h | | Reserved |
| 17h | | Reserved |
| 18h | | Reserved |
| 19h | | Reserved |
| 1Ah | | Reserved |
| 1Bh | | Reserved |
| 1Ch | PRESCALER | Prescaler Control Register |
| 40h | TEST6 | Test register for PLL LOOP |
| 41h | TEST5 | Test register for PLL LOOP |
| 42h | TEST4 | Test register for PLL LOOP (must be updated as specified) |
| 43h | TEST3 | Test register for VCO |
| 44h | TEST2 | Test register for Calibration |
| 45h | TEST1 | Test register for Calibration |
| 46h | TEST0 | Test register for Calibration |

MAIN Register (00h)

| REGISTER | NAME | Default value | Active | Description |
|----------|---------|---------------|--------|---|
| MAIN[7] | - | - | - | Not used |
| MAIN[6] | F_REG | - | - | Selection of Frequency Register, 0 : Register A, 1 : Register B |
| MAIN[5] | - | - | - | Not used |
| MAIN[4] | TX_PD | - | H | Power Down of Signal Interface and PA |
| MAIN[3] | FS_PD | - | H | Power Down of Frequency Synthesiser |
| MAIN[2] | CORE_PD | - | H | Power Down of Crystal Oscillator Core |
| MAIN[1] | BIAS_PD | - | H | Power Down of BIAS (Global_Current_Generator) and Crystal Oscillator Buffer |
| MAIN[0] | RESET_N | - | L | Reset, active low. Writing RESET_N low will write default values to all other registers than MAIN. Bits in MAIN do not have a default value, and will be written directly through the configurations interface. Must be set high to complete reset. |

FREQ_2A Register (01h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|---------------|---------------|--------|-----------------------------------|
| FREQ_2A[7:0] | FREQ_A[23:16] | 01110101 | - | 8 MSB of frequency control word A |

FREQ_1A Register (02h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|--------------|---------------|--------|---|
| FREQ_1A[7:0] | FREQ_A[15:8] | 10100000 | - | Bit 15 to 8 of frequency control word A |

FREQ_0A Register (03h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|-------------|---------------|--------|-----------------------------------|
| FREQ_0A[7:0] | FREQ_A[7:0] | 11001011 | - | 8 LSB of frequency control word A |

FREQ_2B Register (04h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|---------------|---------------|--------|-----------------------------------|
| FREQ_2B[7:0] | FREQ_B[23:16] | 01110101 | - | 8 MSB of frequency control word B |

FREQ_1B Register (05h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|--------------|---------------|--------|---|
| FREQ_1B[7:0] | FREQ_B[15:8] | 10100101 | - | Bit 15 to 8 of frequency control word B |

FREQ_0B Register (06h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|-------------|---------------|--------|-----------------------------------|
| FREQ_0B[7:0] | FREQ_B[7:0] | 01001110 | - | 8 LSB of frequency control word B |

FSEP1 Register (07h)

| REGISTER | NAME | Default value | Active | Description |
|------------|---------------|---------------|--------|---------------------------------------|
| FSEP1[7:3] | - | - | - | Not used |
| FSEP1[2:0] | FSEP_MSB[2:0] | 000 | - | 3 MSB of frequency separation control |

FSEP0 Register (08h)

| REGISTER | NAME | Default value | Active | Description |
|------------|---------------|---------------|--------|---------------------------------------|
| FSEP0[7:0] | FSEP_LSB[7:0] | 01011001 | - | 8 LSB of frequency separation control |

CURRENT Register (09h)

| REGISTER | NAME | Default value | Active | Description |
|--------------|------------------|---------------|--------|--|
| CURRENT[7:4] | VCO_CURRENT[3:0] | 1100 | - | Control of current in VCO core 0000 : 160 μ A 0001 : 320 μ A 0010 : 480 μ A 0011 : 630 μ A 0100 : 790 μ A 0101 : 950 μ A 0110 : 1100 μ A 0111 : 1250 μ A 1000 : 1560 μ A, use for f < 500 MHz 1001 : 1720 μ A 1010 : 1870 μ A 1011 : 2030 μ A 1100 : 2180 μ A 1101 : 2340 μ A 1110 : 2490 μ A 1111 : 2640 μ A, use for f > 500 MHz |
| CURRENT[3:2] | - | - | | Not used |
| CURRENT[1:0] | PA_DRIVE[1:0] | 10 | | Control of current in VCO buffer for PA 00 : 1mA 01 : 2mA, use for TX, f < 500 MHz 10 : 3mA 11 : 4mA, use for TX, f > 500 MHz |

XOSC Register (0Ah)

| REGISTER | NAME | Default value | Active | Description |
|-----------|-------------|---------------|--------|--|
| XOSC[7:1] | - | - | - | Not used |
| XOSC[0] | XOSC_BYPASS | 0 | - | 0 : Internal XOSC enabled 1 : Power-Down of XOSC, external CLK used |

PA_POW Register (0Bh)

| REGISTER | NAME | Default value | Active | Description |
|-------------|-------------------|---------------|--------|--|
| PA_POW[7:4] | PA_HIGHPOWER[3:0] | 0000 | - | Control of output power in high power array. Should be 0000 in PD mode. See Table 3 page 25 for details. |
| PA_POW[3:0] | PA_LOWPOWER[3:0] | 1111 | - | Control of output power in low power array. Should be 0000 in PD mode. See Table 3 page 25 for details. |

PLL Register (0Ch)

| REGISTER | NAME | Default value | Active | Description |
|----------|---------------|---------------|--------|---|
| PLL[7] | EXT_FILTER | 0 | - | 1 : External loop filter 0 : Internal loop filter 1-to-0 transition samples F_COMP comparator when BREAK_LOOP=1 (TEST3) |
| PLL[6:3] | REFDIV[3:0] | 0010 | - | Reference divider 0000 : Not allowed 0001 : Not allowed 0010 : Divide by 2 0011 : Divide by 3 1111 : Divide by 15 |
| PLL[2] | ALARM_DISABLE | 0 | h | 0 : Alarm function enabled 1 : Alarm function disabled |
| PLL[1] | ALARM_H | - | - | Status bit for tuning voltage out of range (too close to VDD) |
| PLL[0] | ALARM_L | - | - | Status bit for tuning voltage out of range (too close to GND) |

LOCK Register (0Dh)

| REGISTER | NAME | Default value | Active | Description |
|-----------|-------------------|---------------|--------|---|
| LOCK[7:4] | LOCK_SELECT[3:0] | 0000 | - | Selection of signals to CHP_OUT (LOCK) pin 0000 : Normal, pin can be used as CHP_OUT 0001 : LOCK_CONTINUOUS (active high) 0010 : LOCK_INSTANT (active high) 0011 : ALARM_H (active high) 0100 : ALARM_L (active high) 0101 : CAL_COMPLETE (active high) 0110 : Not used 0111 : REFERENCE_DIVIDER Output 1000 : TX_PDB (active high, activates external PA when TX_PD=0) 1001 : Not used 1010 : Not used 1011 : Not used 1100 : Not used 1101 : Not used 1110 : N_DIVIDER Output 1111 : F_COMP |
| LOCK[3] | PLL_LOCK_ACCURACY | 0 | - | 0 : Sets Lock Threshold = 127, Reset Lock Threshold = 111. Corresponds to a worst case accuracy of 0.7% 1 : Sets Lock Threshold = 31, Reset Lock Threshold = 15. Corresponds to a worst case accuracy of 2.8% |
| LOCK[2] | PLL_LOCK_LENGTH | 0 | - | 0 : Normal PLL lock window 1 : Not used |
| LOCK[1] | LOCK_INSTANT | - | - | Status bit from Lock Detector |
| LOCK[0] | LOCK_CONTINUOUS | - | - | Status bit from Lock Detector |

CAL Register (0Eh)

| REGISTER | NAME | Default value | Active | Description |
|----------|--------------|---------------|--------|--|
| CAL[7] | CAL_START | 0 | ↑ | ↑ 1 : Calibration started 0 : Calibration inactive CAL_START must be set to 0 after calibration is done |
| CAL[6] | CAL_DUAL | 0 | H | 1 : Store calibration in both A and B 0 : Store calibration in A or B defined by MAIN[6] |
| CAL[5] | CAL_WAIT | 0 | H | 1 : Normal Calibration Wait Time 0 : Half Calibration Wait Time The calibration time is proportional to the internal reference frequency. 2 MHz reference frequency gives 14 ms wait time. |
| CAL[4] | CAL_CURRENT | 0 | H | 1 : Calibration Current Doubled 0 : Normal Calibration Current |
| CAL[3] | CAL_COMPLETE | 0 | H | Status bit defining that calibration is complete |
| CAL[2:0] | CAL_ITERATE | 101 | H | Iteration start value for calibration DAC 000 - 101: Not used 110 : Normal start value 111 : Not used |

MODEM0 Register (11h)

| REGISTER | NAME | Default value | Active | Description |
|-------------|------------------|---------------|--------|---|
| MODEM0[7] | - | - | - | Not used |
| MODEM0[6:4] | BAUDRATE[2:0] | 010 | - | 000 : 0.6 kBaud 001 : 1.2 kBaud 010 : 2.4 kBaud 011 : 4.8 kBaud 100 : 9.6 kBaud 101 : 19.2 kBaud 110 : 38.4 kBaud 111 : 76.8 kBaud |
| MODEM0[3:2] | DATA_FORMAT[1:0] | 01 | - | 00 : NRZ operation. 01 : Manchester operation 10 : Transparent Asynchronous UART operation 11 : Not used |
| MODEM0[1:0] | XOSC_FREQ[1:0] | 00 | - | Selection of XTAL frequency range 00 : 3MHz - 4MHz crystal, 3.6864MHz recommended 01 : 6MHz - 8MHz crystal, 7.3728MHz recommended 10 : 9MHz - 12MHz crystal, 11.0592 MHz recommended 11 : 12MHz - 16MHz crystal, 14.7456MHz recommended |

FSCTRL Register (13h)

| REGISTER | NAME | Default value | Active | Description |
|-------------|------------|---------------|--------|---|
| FSCTRL[7:4] | - | - | - | Not used |
| FSCTRL[3:1] | | | | Reserved |
| FSCTRL[0] | FS_RESET_N | 1 | L | Separate reset of frequency synthesizer |

PRESCALER Register (1Ch)

| REGISTER | NAME | Default value | Active | Description |
|----------------|-------------------|---------------|--------|--|
| PRESCALER[7:6] | PRE_SWING[1:0] | 00 | - | Prescaler swing. Fractions for PRE_CURRENT[1:0] = 00 00 : 1 * Nominal Swing 01 : 2/3 * Nominal Swing 10 : 7/3 * Nominal Swing 11 : 5/3 * Nominal Swing |
| PRESCALER[5:4] | PRE_CURRENT [1:0] | 00 | - | Prescaler current scaling 00 : 1 * Nominal Current 01 : 2/3 * Nominal Current 10 : 1/2 * Nominal Current 11 : 2/5 * Nominal Current |
| PRESCALER[3] | BYPASS_R | 0 | H | Bypass the resistor in the PLL loop filter 0 : Not bypassed 1 : Bypassed |
| PRESCALER[2] | DISCONNECT_C | 0 | - | Disconnect the capacitor in the PLL loop filter 0 : Capacitor connected 1 : Capacitor disconnected. Use for data rate 38.4 and 76.8 kBaud only. |
| PRESCALER[1:0] | - | - | - | Not used |

TEST6 Register (for test only, 40h)

| REGISTER | NAME | Default value | Active | Description |
|------------|----------------|---------------|--------|--|
| TEST6[7] | LOOPFILTER_TP1 | 0 | - | 1 : Select testpoint 1 to CHP_OUT 0 : CHP_OUT tied to GND |
| TEST6 [6] | LOOPFILTER_TP2 | 0 | - | 1 : Select testpoint 2 to CHP_OUT 0 : CHP_OUT tied to GND |
| TEST6 [5] | CHP_OVERRIDE | 0 | - | 1 : use CHP_CO[4:0] value 0 : use calibrated value |
| TEST6[4:0] | CHP_CO[4:0] | 10000 | - | Charge_Pump Current DAC override value |

TEST5 Register (for test only, 41h)

| REGISTER | NAME | Default value | Active | Description |
|------------|--------------|---------------|--------|---|
| TEST5[7:6] | - | - | - | Not used |
| TEST5[5] | CHP_DISABLE | 0 | - | 1 : CHP up and down pulses disabled 0 : normal operation |
| TEST5[4] | VCO_OVERRIDE | 0 | - | 1 : use VCO_AO[3:0] value 0 : use calibrated value |
| TEST5[3:0] | VCO_AO[3:0] | 1000 | - | VCO_ARRAY override value |

TEST4 Register (for test only, 42h)

| REGISTER | NAME | Default value | Active | Description |
|------------|------------|---------------|--------|--|
| TEST4[7:6] | - | - | - | Not used |
| TEST4[5:0] | L2KIO[5:0] | 100101 | h | Constant setting charge pump current scaling/rounding factor. Sets Bandwidth of PLL. Use 3Fh for 38.4 and 76.8 kBaud |

TEST3 Register (for test only, 43h)

| REGISTER | NAME | Default value | Active | Description |
|------------|--------------|---------------|--------|---|
| TEST3[7:5] | - | - | - | Not used |
| TEST3[4] | BREAK_LOOP | 0 | - | 1 : PLL loop open 0 : PLL loop closed |
| TEST3[3:0] | CAL_DAC_OPEN | 0100 | - | Calibration DAC override value, active when BREAK_LOOP =1 |

TEST2 Register (for test only, 44h)

| REGISTER | NAME | Default value | Active | Description |
|------------|-------------------|---------------|--------|--|
| TEST2[7:5] | - | - | - | Not used |
| TEST2[4:0] | CHP_CURRENT [4:0] | - | - | Status vector defining applied CHP_CURRENT value |

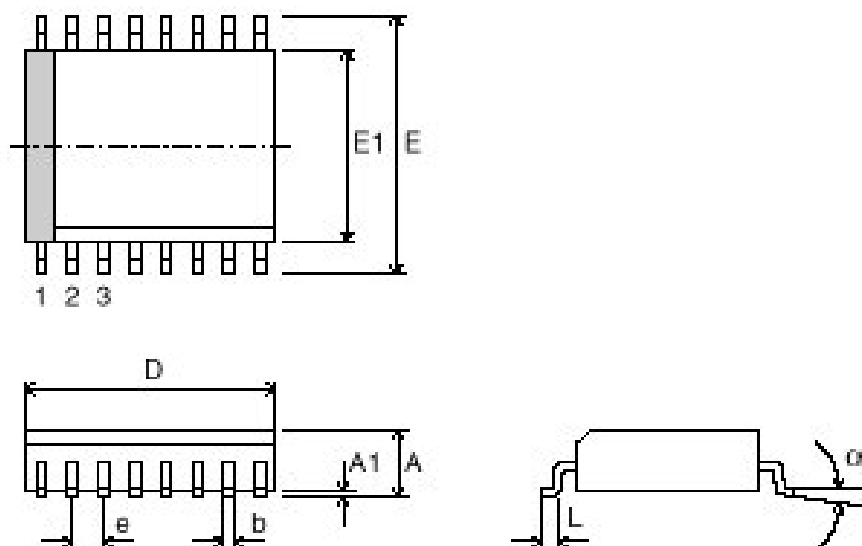
TEST1 Register (for test only, 45h)

| REGISTER | NAME | Default value | Active | Description |
|------------|--------------|---------------|--------|--|
| TEST1[7:4] | - | - | - | Not used |
| TEST1[3:0] | CAL_DAC[3:0] | - | - | Status vector defining applied Calibration DAC value |

TEST0 Register (for test only, 46h)

| REGISTER | NAME | Default value | Active | Description |
|------------|----------------|---------------|--------|--|
| TEST0[7:4] | - | - | - | Not used |
| TEST0[3:0] | VCO_ARRAY[3:0] | - | - | Status vector defining applied VCO_ARRAY value |

Package Description (TSSOP-24)



Note: The figure is an illustration only.

| Thin Shrink Small Outline Package (TSSOP) | | | | | | | | | | | |
|---|-----|-----|------|------|------|------|------|------|------|-------|----------|
| | | D | E1 | E | A | A1 | E | B | L | Copl. | α |
| TSSOP 24 | Min | 7.7 | 4.30 | 6.40 | 1.20 | 0.15 | 0.65 | 0.19 | 0.45 | 0.10 | 0° |
| | Max | 7.9 | 4.50 | | | | | | | | |

All dimensions in mm

Soldering Information

Recommended soldering profile is according to IPC/JEDEC J-STD-020B, July 2002.

Plastic Tube Specification

TSSOP 4.4mm (.173") antistatic tube.

| Tube Specification | | | | |
|--------------------|------------|-------------|-------------|----------------|
| Package | Tube Width | Tube Height | Tube Length | Units per Tube |
| TSSOP 24 | 268 mil | 80 mil | 20" | 62 |

Carrier Tape and Reel Specification

Carrier tape and reel is in accordance with EIA Specification 481.

| Tape and Reel Specification | | | | | |
|-----------------------------|------------|-----------------|------------|---------------|----------------|
| Package | Tape Width | Component Pitch | Hole Pitch | Reel Diameter | Units per Reel |
| TSSOP 24 | 16 mm | 8 mm | 4 mm | 13" | 2500 |

Ordering Information

| Ordering part number | Description | MOQ |
|----------------------|-------------------------------------|----------------------|
| CC1050 | Single Chip RF Transceiver | 62 (tube) |
| CC1050/T&R | Single Chip RF Transceiver | 2500 (tape and reel) |
| CC1050DK-433 | CC1050 Development Kit, 433 MHz | 1 |
| CC1050DK-868 | CC1050 Development Kit, 868/915 MHz | 1 |
| CC1050SK | CC1050 Sample Kit (5 pcs) | 1 |

MOQ = Minimum Order Quantity

General Information

Document Revision History

| Revision | Date | Description/Changes |
|----------|-------------|--|
| 1.1 | April 2004 | Shaping feature removed L1 changed to 0603 size Crystal oscillator information added Preliminary version removed Minor corrections and editorial changes |
| 1.2 | August 2004 | Application circuit and BOM simplified Description in the FSCTRL register changed KOA inductor removed in BOM Additional information on LC-filter |

Disclaimer

Chipcon AS believes the information contained herein is correct and accurate at the time of this printing. However, Chipcon AS reserves the right to make changes to this product without notice. Chipcon AS does not assume any responsibility for the use of the described product; neither does it convey any license under its patent rights, or the rights of others. The latest updates are available at the Chipcon website or by contacting Chipcon directly.

To the extent possible, major changes of product specifications and functionality will be stated in product specific Errata Notes published at the Chipcon website. Customers are encouraged to sign up for the Developer's Newsletter for the most recent updates on products and support tools.

When a product is discontinued this will be done according to Chipcon's procedure for obsolete products as described in Chipcon's Quality Manual. This includes informing about last-time-buy options. The Quality Manual can be downloaded from Chipcon's website.

Trademarks

SmartRF® is a registered trademark of Chipcon AS. SmartRF® is Chipcon's RF technology platform with RF library cells, modules and design expertise. Based on SmartRF® technology Chipcon develops standard component RF circuits as well as full custom ASICs based on customer requirements and this technology.

All other trademarks, registered trademarks and product names are the sole property of their respective owners.

Life Support Policy

This Chipcon product is not designed for use in life support appliances, devices, or other systems where malfunction can reasonably be expected to result in significant personal injury to the user, or as a critical component in any life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness. Chipcon AS customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Chipcon AS for any damages resulting from any improper use or sale.

© 2004, Chipcon AS. All rights reserved.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

| Products | | Applications | |
|--------------------|--|---------------------|--|
| Amplifiers | amplifier.ti.com | Audio | www.ti.com/audio |
| Data Converters | dataconverter.ti.com | Automotive | www.ti.com/automotive |
| DSP | dsp.ti.com | Broadband | www.ti.com/broadband |
| Interface | interface.ti.com | Digital Control | www.ti.com/digitalcontrol |
| Logic | logic.ti.com | Military | www.ti.com/military |
| Power Mgmt | power.ti.com | Optical Networking | www.ti.com/opticalnetwork |
| Microcontrollers | microcontroller.ti.com | Security | www.ti.com/security |
| Low Power Wireless | www.ti.com/lpw | Telephony | www.ti.com/telephony |
| | | Video & Imaging | www.ti.com/video |
| | | Wireless | www.ti.com/wireless |

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265

Copyright © 2007, Texas Instruments Incorporated

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru

www.lifeelectronics.ru